



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



The MS Series of thermoelectric modules (TEMs) are designed to reach cool down temperatures that are not achievable with single stage TEMs.



This product line is available in numerous heat pumping capacities, geometric shapes and temperature differentials. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the MS Series is designed for higher current and lower heat-pumping applications.

Americas: +1.919.597.7300

Europe: +46.31.420530

Asia: +86.755.2714.1166

ets.sales@lairdtech.com

www.lairdtech.com

FEATURES

- High temperature differential
- Precise temperature control
- Reliable solid state operation
- Environmentally friendly
- DC operation
- RoHS compliant

APPLICATIONS

- CCD cameras
- Electron microscope
- Calibration equipment
- Photonics laser systems
- Gas analyzers
- Infrared (IR) sensors
- Guidance systems

SPECIFICATIONS

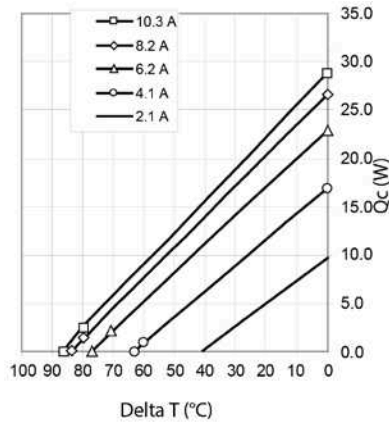
PERFORMANCE

Hot Side Temperature (°C)	25°C
Qmax (Watts)	28.9
Delta Tmax (°C)	87
I _{max} (Amps)	10.3
V _{max} (Volts)	8.2

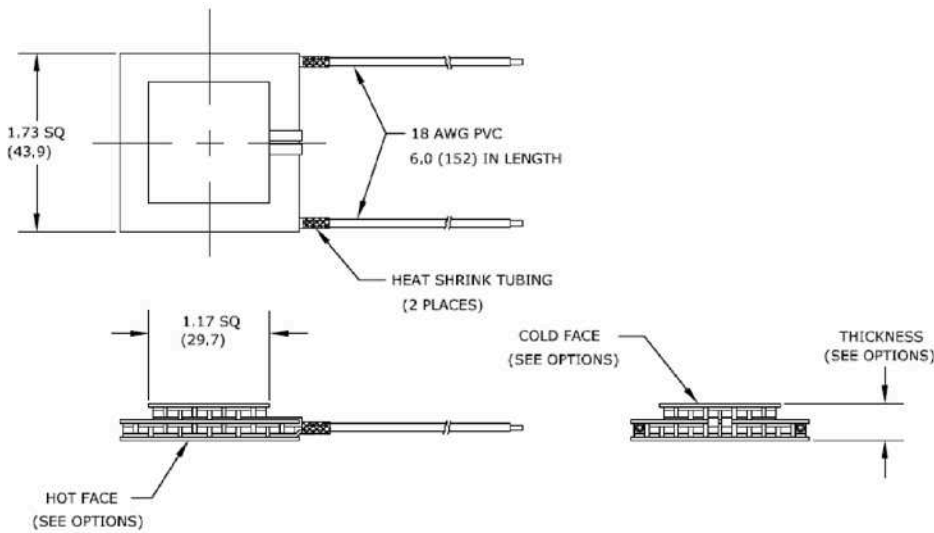
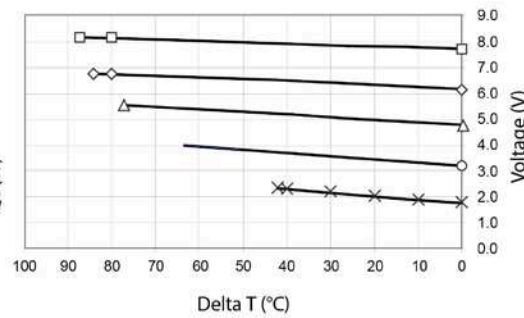
SUFFIX	THICKNESS PRIOR TO TINNING	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
00	0.360" ± 0.015"	0.015" / 0.015"	Metallized	Metallized	6.0"
11	0.352" ± 0.015"	0.015" / 0.015"	Lapped	Lapped	6.0"
22	0.360" ± 0.015"	0.015" / 0.015"	Pre-tinned	Pre-tinned	6.0"

Performance Curves at Th = 25°C

THERMO



ELECTRIC



Ceramic Material: 100% (Al₂O₃)

Solder Construction: 138°C, Bismuth Tin (BiSn)

OPERATING TIPS

- Max operating temperature: 80°C
- Do not exceed I_{max} or V_{max} when operating module
- Reference assembly guidelines for recommended installation
- Solder tinning also available on metallized ceramics

LAIRD-ETS-MS2-102-22-22-17-17-DATA-SHEET-101416

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user. Laird Technologies makes no warranties as to the fitness, merchantability, suitability or non-infringement of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies' Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2016 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trademarks or registered trademarks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights.